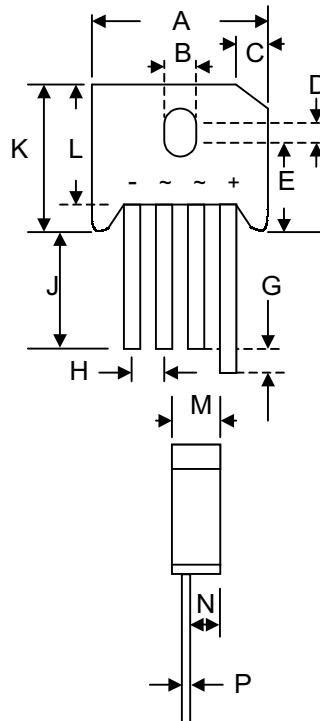


Features

- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- UL Recognized File # E223064

Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 8.0 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



KBU				
Dim	Min	Max	Min	Max
A	22.70	23.70	0.894	0.933
B	3.80	4.10	0.150	0.161
C	4.20	4.70	0.165	0.185
D	1.70	2.20	0.067	0.087
E	10.30	11.30	0.406	0.445
G	4.50	6.80	0.177	0.268
H	4.60	5.60	0.181	0.220
J	25.40	—	1.00	—
K	—	19.30	—	0.760
L	16.80	17.80	0.661	0.701
M	6.60	7.10	0.260	0.280
N	4.70	5.20	0.185	0.205
P	1.20	1.30	0.047	0.051
In mm		In inch		

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	KBU 1000	KBU 1001	KBU 1002	KBU 1004	KBU 1006	KBU 1008	KBU 1010	Unit
Peak Repetitive Reverse Voltage	V _{RRM}								
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_c = 100^\circ\text{C}$	I _o				10				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}				300				A
Forward Voltage (per element) @ $I_F = 5.0\text{A}$	V _{FM}				1.0				V
Peak Reverse Current @ $T_c = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_c = 100^\circ\text{C}$	I _R				10	1.0			μA mA
Rating for Fusing ($t < 8.3\text{ms}$) (Note 1)	I ² _t				373				A^2s
Typical Thermal Resistance (Note 2)	R _{θJC}				8.0				K/W
Operating and Storage Temperature Range	T _j , T _{STG}				-65 to +150				°C

Note: 1. Non-repetitive for $t > 1\text{ms}$ and $< 8.3\text{ms}$.

2. Thermal resistance junction to case per element mounted on PC board with 13.0x13.0x0.03mm thick land areas.

Data Sheet 1314, Rev. A

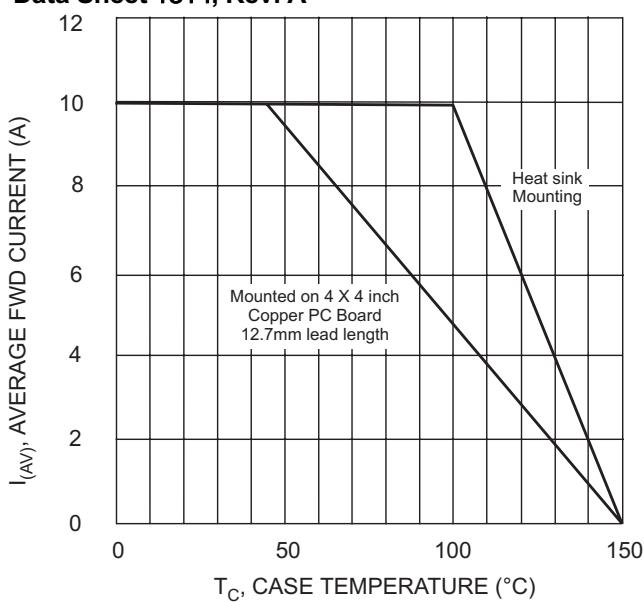


Fig. 1 Forward Current Derating Curve

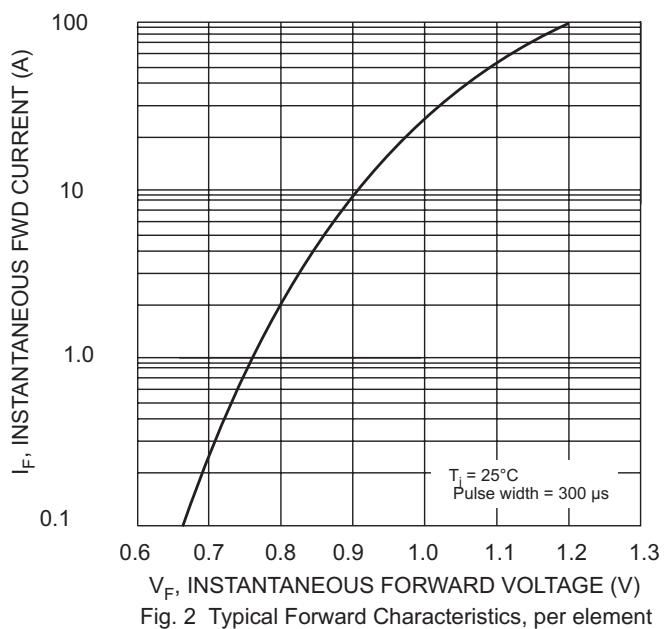


Fig. 2 Typical Forward Characteristics, per element

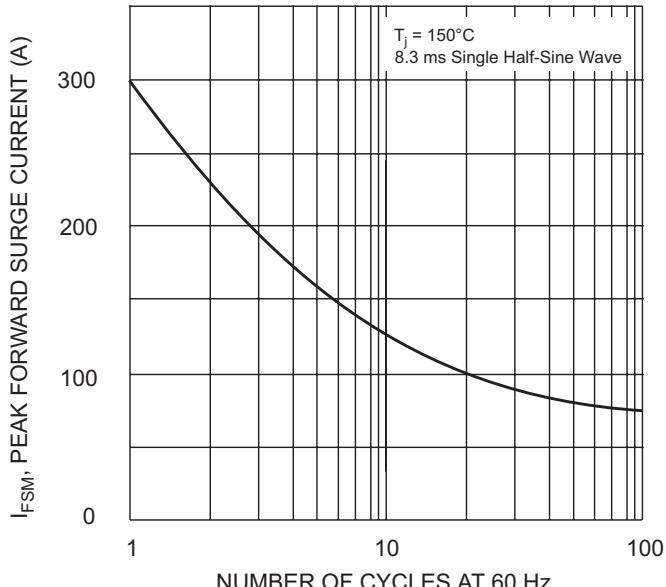


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

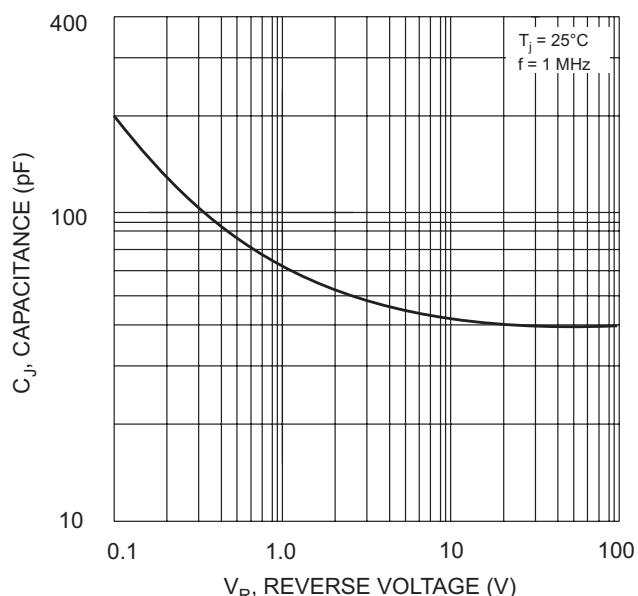


Fig. 4 Typical Junction Capacitance per element

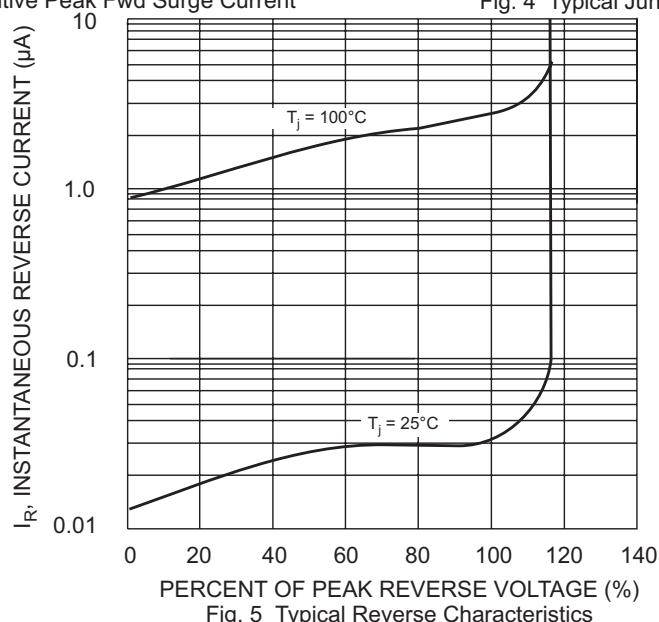


Fig. 5 Typical Reverse Characteristics

TECHNICAL DATA

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